# N-channel Enhancement Mode Power MOSFET

## Features

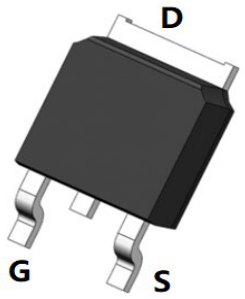
- VDS= 60V, ID= 50A
  RDS(ON) < 12 mΩ @ VGS = 10V
  RDS(ON) < 16 mΩ @ VGS =4.5V

## General Features

- Advanced Trench Technology
- Provide Excellent RDS(ON) and Low Gate Charge
- Lead Free and Green Available

*100% UIS TESTED!*
*100% ΔVds TESTED!*

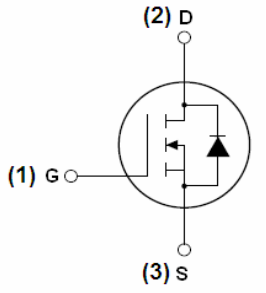
RoHS




TO-252-2L Top View




Pin Assignment




Schematic Diagram

### Absolute Maximum Ratings ($T_C$=25℃unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|---|---|---|---|
| Drain-Source Voltage | $V_{DS}$ | 60 | V |
| Gate-Source Voltage | $V_{GS}$ | ±20 | V |
| Drain Current-Continuous | $I_D$ | 50 | A |
| Drain Current-Continuous($T_C$=100℃) | $I_D$ (100℃) | 35.4 | A |
| Pulsed Drain Current | $I_{DM}$ | 200 | A |
| Maximum Power Dissipation | $P_D$ | 85 | W |
| Derating factor | | 0.57 | W/℃ |
| Single pulse avalanche energy (Note 5) | $E_{AS}$ | 200 | mJ |
| Operating Junction and Storage Temperature Range | $T_J$,$T_{STG}$ | -55 To 175 | ℃ |

### Thermal Characteristic

| | | | |
|---|---|---|---|
| Thermal Resistance,Junction-to-Case(Note 2) | $R_{\theta JC}$ | 1.8 | ℃/W |

## Electrical Characteristics ($T_C$=25℃unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| **Off Characteristics** | | | | | | |
| Drain-Source Breakdown Voltage | $BV_{DSS}$ | $V_{GS}$=0V $I_D$=250μA | 60 | - | - | V |
| Zero Gate Voltage Drain Current | $I_{DSS}$ | $V_{DS}$=60V,$V_{GS}$=0V | - | - | 1 | μA |
| Gate-Body Leakage Current | $I_{GSS}$ | $V_{GS}$=±20V,$V_{DS}$=0V | - | - | ±100 | nA |
| **On Characteristics** (Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}$=$V_{GS}$,$I_D$=250μA | 1.0 | | 3.0 | V |
| Drain-Source On-State Resistance | $R_{DS(ON)}$ | $V_{GS}$=10V, $I_D$=20A | - | 12 | | mΩ |
| | | $V_{GS}$=4.5V, $I_D$=20A | - | 16 | | mΩ |
| Forward Transconductance | $g_{FS}$ | $V_{DS}$=5V,$I_D$=20A | 18 | - | - | S |
| **Dynamic Characteristics** (Note4) | | | | | | |
| Input Capacitance | $C_{lss}$ | $V_{DS}$=30V,$V_{GS}$=0V, F=1.0MHz | - | 1630 | - | PF |
| Output Capacitance | $C_{oss}$ | | - | 113 | - | PF |
| Reverse Transfer Capacitance | $C_{rss}$ | | - | 97 | - | PF |
| **Switching Characteristics** (Note 4) | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}$=30V, $R_L$=6.7Ω $V_{GS}$=5V,$R_G$=3Ω | - | 15 | - | nS |
| Turn-on Rise Time | $t_r$ | | - | 20 | - | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 120 | - | nS |
| Turn-Off Fall Time | $t_f$ | | - | 15.6 | - | nS |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}$=30V, $R_L$=6.7Ω $V_{GS}$=10V,$R_G$=3Ω | - | 7.4 | - | nS |
| Turn-on Rise Time | $t_r$ | | - | 5.1 | - | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 28.2 | - | nS |
| Turn-Off Fall Time | $t_f$ | | - | 5.5 | - | nS |
| Total Gate Charge | $Q_g$ | $V_{DS}$=30V,$I_D$=20A, $V_{GS}$=10V | - | 39 | | nC |
| Gate-Source Charge | $Q_{gs}$ | | - | 7 | | nC |
| Gate-Drain Charge | $Q_{gd}$ | | - | 8.5 | | nC |
| **Drain-Source Diode Characteristics** | | | | | | |
| Diode Forward Voltage (Note 3) | $V_{SD}$ | $V_{GS}$=0V,$I_S$=20A | - | | 1.2 | V |
| Diode Forward Current (Note 2) | $I_S$ | | - | - | 50 | A |
| Reverse Recovery Time | $t_{rr}$ | TJ = 25°C, IF =20A di/dt = 100A/μs (Note3) | - | 28 | - | nS |
| Reverse Recovery Charge | Qrr | | - | 40 | - | nC |
| Forward Turn-On Time | $t_{on}$ | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD) | | | | |

## Notes:

**1.** Repetitive Rating: Pulse width limited by maximum junction temperature.
**2.** Surface Mounted on FR4 Board, t ≤ 10 sec.
**3.** Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
**4.** Guaranteed by design, not subject to production
**5.** EAS condition : Tj=25℃,$V_{DD}$=30V,$V_G$=10V,L=0.5mH,Rg=25Ω

## Typical Electrical and Thermal Characteristics (Curves)

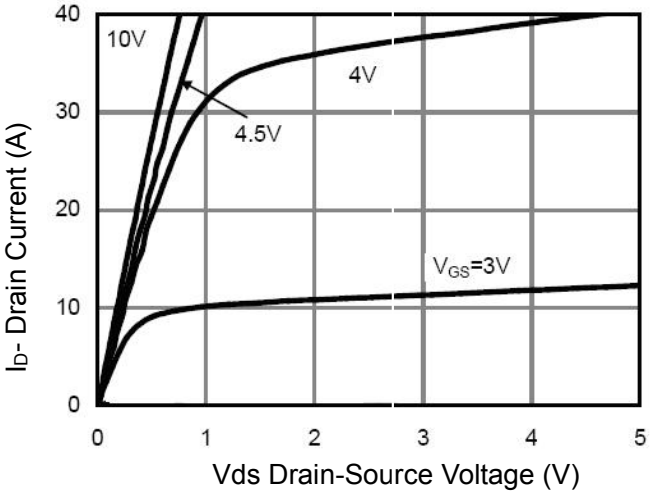



**Figure 1 Output Characteristics**

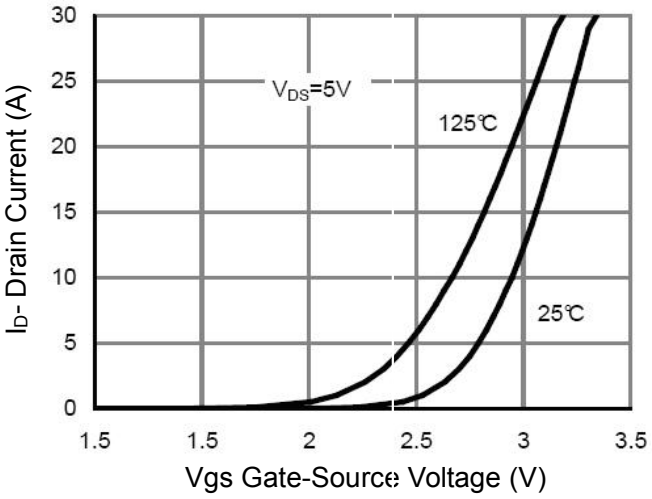



**Figure 2 Transfer Characteristics**

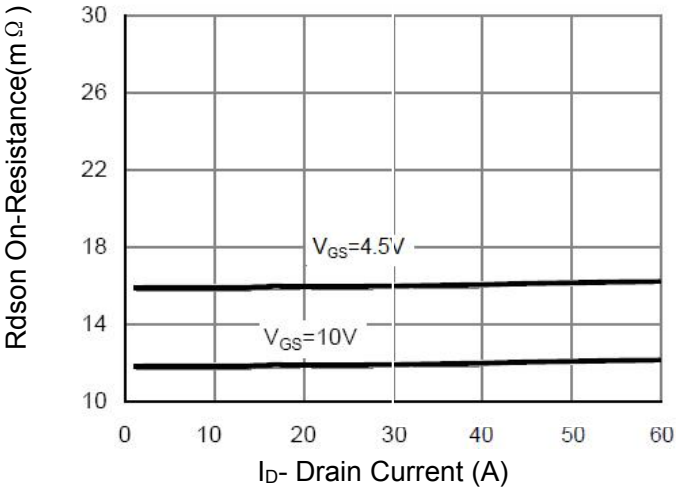



**Figure 3 Rdson- Drain Current**

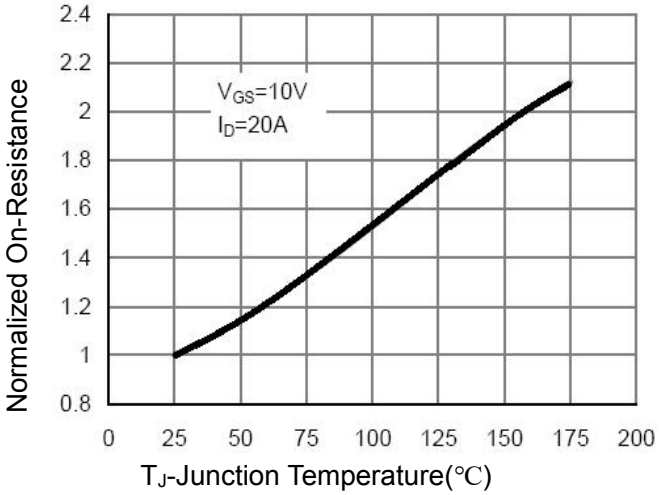



**Figure 4 Rdson-Junction Temperature**

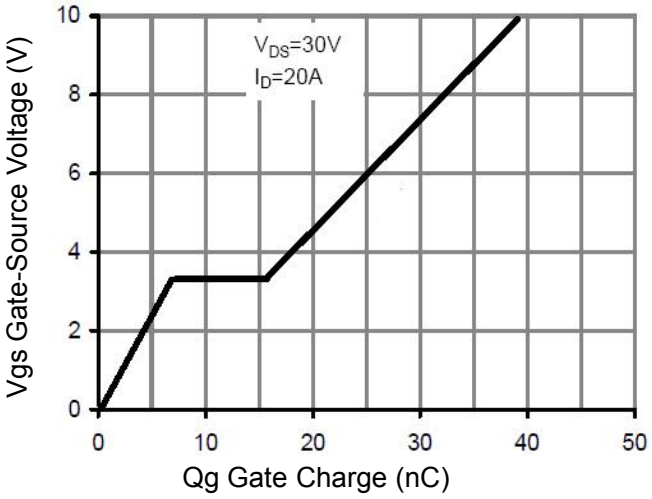



**Figure 5 Gate Charge**

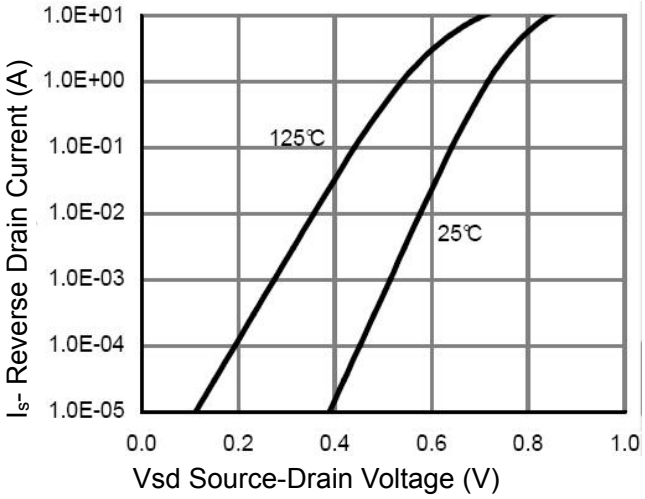



**Figure 6 Source- Drain Diode Forward**

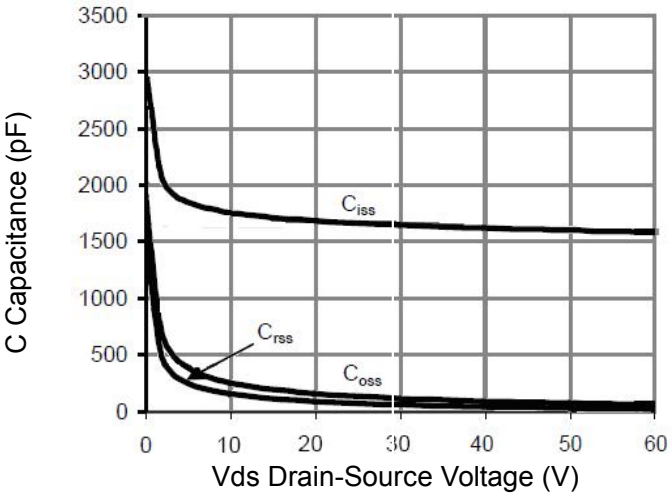



**Figure 7 Capacitance vs Vds**

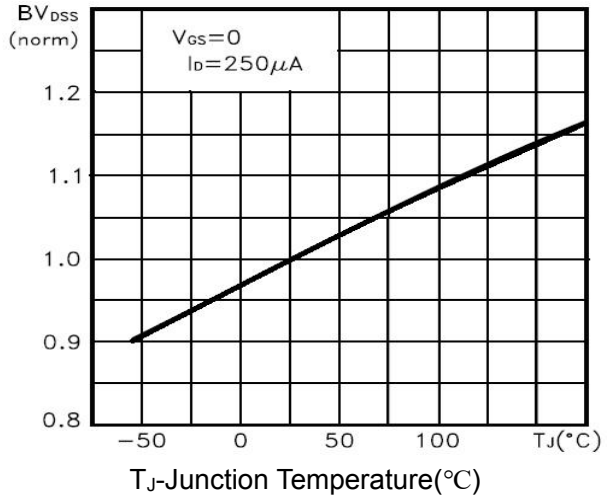



**Figure 9 $BV_{DSS}$ vs Junction Temperature**

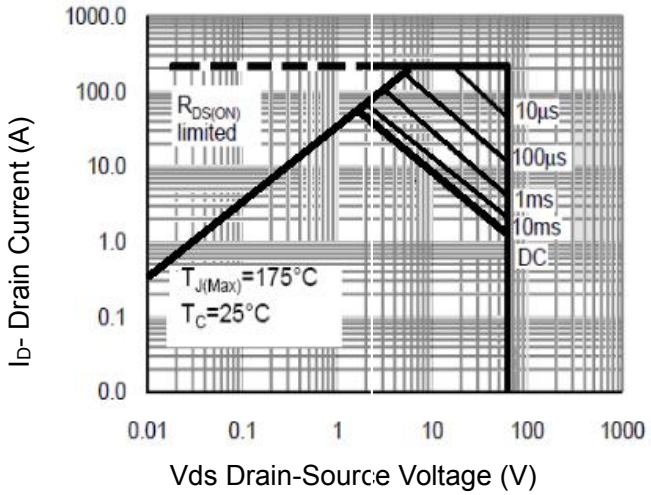



**Figure 8 Safe Operation Area**

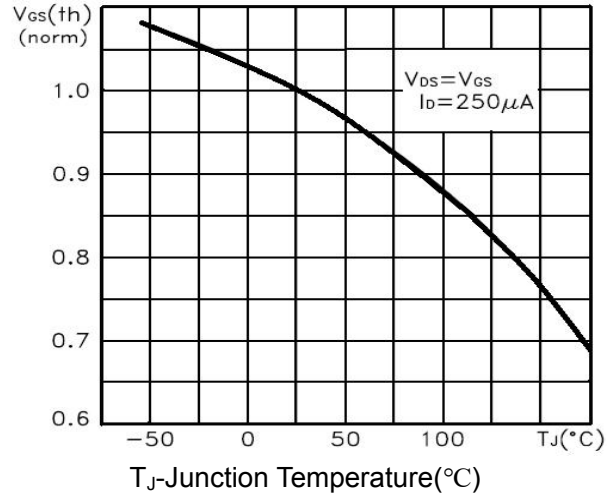



**Figure 10 $V_{GS(th)}$ vs Junction Temperature**

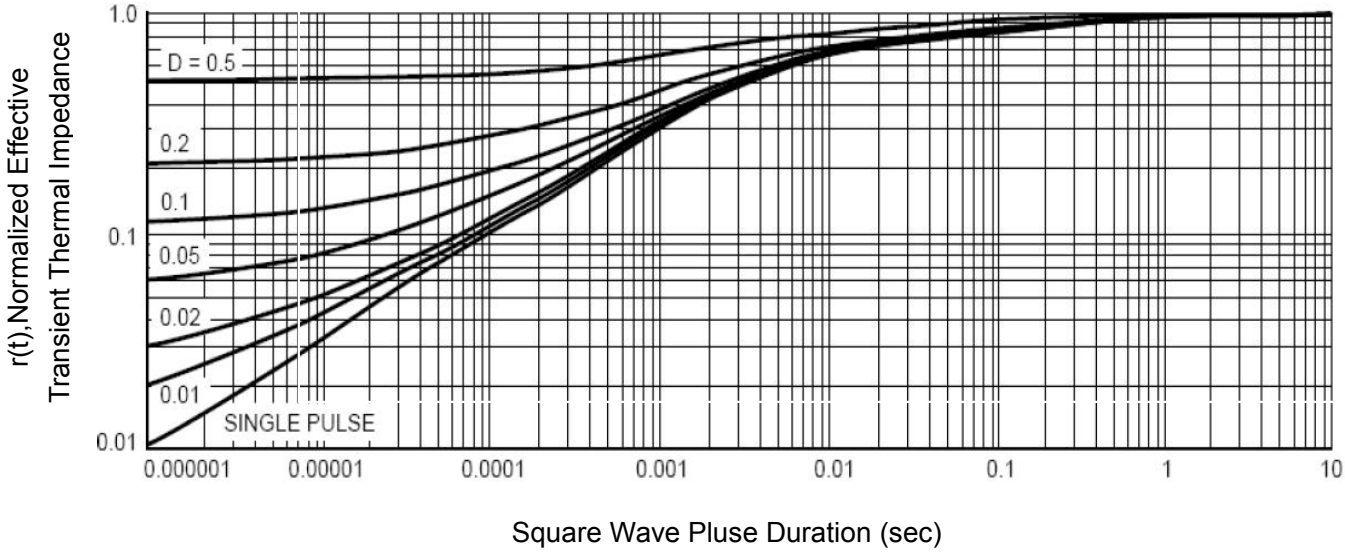



**Figure 11 Normalized Maximum Transient Thermal Impedance**